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OMB No. 0651-0027 (exp. 7/31/2 3)
PATE

07-28-2008



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record the attached documents or the new address(es) below.
2. Name and address of receiving party(ies)
Name: Sony Corporation Internal Address:
Street Address:
1-7-1 Konan Minato-Ku, Tokyo 108-0075 JAPAN City: State: Country: Zip:
Additional name(s) & address(es) Yes X No attached?
This document is being filed together with a new application. B. Patent No.(s) Yes X No
6. Total number of applications and patents involved:
7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00 Authorized to be charged by credit card X Authorized to be charged to deposit account Enclosed None required (government interest not affecting title)
8. Payment Information a. Credit Card Last 4 Numbers Expiration Date b. Deposit Account Number 18-0013 Authorized User Name Christopher M. Tobin
July 22, 2008 Date
Total number of pages including cover sheet, attachments, and documents:

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RECORDATION FORM COVER SHEET (PTO-1595) (supplemental sheet)				
Additional Convey	ring Party(ies)/Exect	ution Date(s) (1. Continued):		
Rintaro Koda (01/10/2	2008) and Norihiko Yam	naguchi (01/10/2008)		
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Additional Applica	ations and/or Patent	s (4. Continued):		
Additional Patent Applicat 4A. Continued:	ion Numbers	Additional Patent Numbers 4B. Continued:		
(Additional numbers	s attached? Yes No		

Docket No.: SON-3771

Docket Number:
ASSIGNMENT
WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING IT
for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my nar and address;
AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be grant therefor in the United States and in any and all foreign countries;
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficience of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, be hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title as interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letter Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all prior rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of American adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue to said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention applications and Letters Patent of the United States and countries foreign thereto;
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawf papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require at prepare at its own expense;
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and document relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known at accessible to me and will testify as to the same in any interference or litigation related thereto;
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.
And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date this application in the spaces that follow: Serial Number: 11/806,884 Filing Date: June 5, 2007
This assignment executed on the dates indicated below.
Yuji MASUI
Name of first or sole inventor Execution date of U.S. Patent Application
Kanagawa, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Zuji Masui

PATENT REEL: 021318 FRAME: 0044

Date of this assignment

January 10, 2008

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PATENT REEL: 021318 FRAME: 0045

Norihiko YAMAGUCHI	
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Signature of Sixth Inventor –	- Date of this assignment
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Signature of seventh inventor	Date of this assignment
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Name of ninth inventor	Execution date of U.S. Patent Application
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PATENT REEL: 021318 FRAME: 0046

RECORDED: 07/23/2008